Abstracts

Avoiding cross talk and feed back effects in packaging coplanar millimeter-wave circuits

T. Krems, A. Tessmann, W.H. Haydl, C. Schmelz and P. Heide. "Avoiding cross talk and feed back effects in packaging coplanar millimeter-wave circuits." 1998 MTT-S International Microwave Symposium Digest 98.2 (1998 Vol. II [MWSYM]): 1091-1094.

The impact of the packaging configuration on cross talk and feed back effects caused by parasitic substrate modes is investigated for coplanar millimeter-wave circuits. It is demonstrated theoretically and by means of several circuit examples that both the mounting configuration and the thickness of the semiconductor substrate of coplanar MIMICs have to be chosen appropriately, in order to avoid circuit degradation or even failure.

❑ Return to main document.